



BUK7S2R0-40H

N-channel 40 V, 2 mOhm standard level MOSFET in LFPAK88

6 April 2021

Product data sheet

1. General description

Automotive qualified N-channel MOSFET using the latest Trench 9 low ohmic superjunction technology, housed in a copper-clip LFPAK88 package. This product has been fully designed and qualified to meet beyond AEC-Q101 requirements delivering high performance and reliability.

2. Features and benefits

- Fully automotive qualified to beyond AEC-Q101:
 - 55 °C to +175 °C rating suitable for thermally demanding environments
- LFPAK88 package:
 - Designed for smaller footprint and improved power density over older wire bond packages such as D²PAK for today's space constrained high power automotive applications
 - Thin package and copper clip enables LFPAK88 to be highly efficient thermally
- LFPAK copper clip technology enabling improvements over wire bond packages by:
 - Increased maximum current capability and excellent current spreading
 - Improved $R_{DS(on)}$
 - Low source inductance
 - Low thermal resistance R_{th}
- LFPAK Gull Wing leads:
 - Flexible leads enabling high Board Level Reliability absorbing mechanical and thermal cycling stress, unlike traditional QFN packages
 - Visual (AOI) soldering inspection, no need for expensive x-ray equipment
 - Easy solder wetting for good mechanical solder joint
- Unique 40 V Trench 9 superjunction technology:
 - Reduced cell pitch and superjunction platform enables lower $R_{DS(on)}$ in the same footprint
 - Improved SOA and avalanche capability compared to standard TrenchMOS
 - Tight $V_{GS(th)}$ limits enable easy paralleling of MOSFETs

3. Applications

- 12 V automotive systems
- 48 V DC/DC systems (on 12 V secondary side)
- Higher power motors, lamps and solenoid control
- Reverse polarity protection
- Ultra high performance power switching

4. Quick reference data

Table 1. Quick reference data

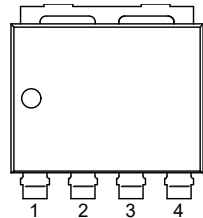
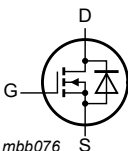
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$		-	-	40	V
I_D	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25\text{ °C}; \text{Fig. 2}$	[1]	-	-	190	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}; \text{Fig. 1}$		-	-	183	W

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; Fig. 11	1.19	1.7	2	mΩ
Dynamic characteristics						
Q _{GD}	gate-drain charge	I _D = 25 A; V _{DS} = 32 V; V _{GS} = 10 V; Fig. 13; Fig. 14	-	9	18	nC
Source-drain diode						
Q _r	recovered charge	I _S = 25 A; dI _S /dt = -100 A/μs; V _{GS} = 0 V; [2]	-	25	-	nC
S	softness factor	V _{DS} = 20 V; T _j = 25 °C	-	0.88	-	

- [1] 190A continuous current has been successfully demonstrated during application. Practically the current will be limited by PCB, thermal design and operating temperature
- [2] includes capacitive recovery

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 LFPAK88 (SOT1235)	 mbb076
2	S	source		
3	S	source		
4	S	source		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK7S2R0-40H	LFPAK88	plastic, single-ended surface-mounted package (LFPAK88); 4 leads; 2 mm pitch; 8 mm x 8 mm x 1.6 mm body	SOT1235

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK7S2R0-40H	7S2R040H

8. Limiting values

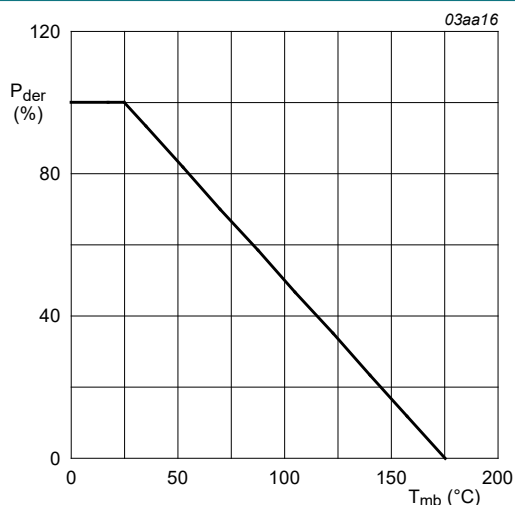
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	40	V

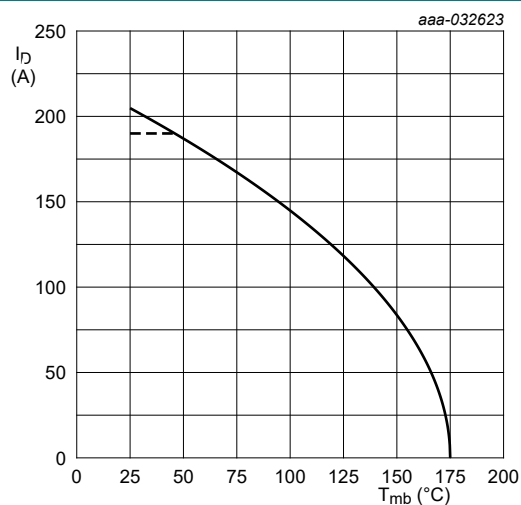
Symbol	Parameter	Conditions		Min	Max	Unit
V_{GS}	gate-source voltage	DC; $T_j = 175\text{ }^{\circ}\text{C}$		-10	20	V
P_{tot}	total power dissipation	$T_{mb} = 25\text{ }^{\circ}\text{C}$; Fig. 1		-	183	W
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$; Fig. 2	[1]	-	190	A
I_{DM}	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$; Fig. 3		-	819	A
T_{stg}	storage temperature			-55	175	$^{\circ}\text{C}$
T_j	junction temperature			-55	175	$^{\circ}\text{C}$
Source-drain diode						
I_S	source current	$T_{mb} = 25\text{ }^{\circ}\text{C}$	[2]	-	183	A
I_{SM}	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$		-	819	A
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 120\text{ A}$; $V_{sup} \leq 40\text{ V}$; $R_{GS} = 50\text{ }\Omega$; $V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; unclamped; Fig. 4	[3] [4]	-	112	mJ
I_{AS}	non-repetitive avalanche current	$V_{sup} = 40\text{ V}$; $V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $R_{GS} = 50\text{ }\Omega$	[5]	-	131	A

- [1] 190A continuous current has been successfully demonstrated during application. Practically the current will be limited by PCB, thermal design and operating temperature
- [2] 183A continuous current has been successfully demonstrated during application. Practically the current will be limited by PCB, thermal design and operating temperature
- [3] Single-pulse avalanche rating limited by maximum junction temperature of 175 $^{\circ}\text{C}$.
- [4] Refer to application note AN10273 for further information.
- [5] Protected by 100% test.



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

Fig. 1. Normalized total power dissipation as a function of mounting base temperature



$V_{GS} \geq 10\text{ V}$

(1) 190A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

Fig. 2. Continuous drain current as a function of mounting base temperature

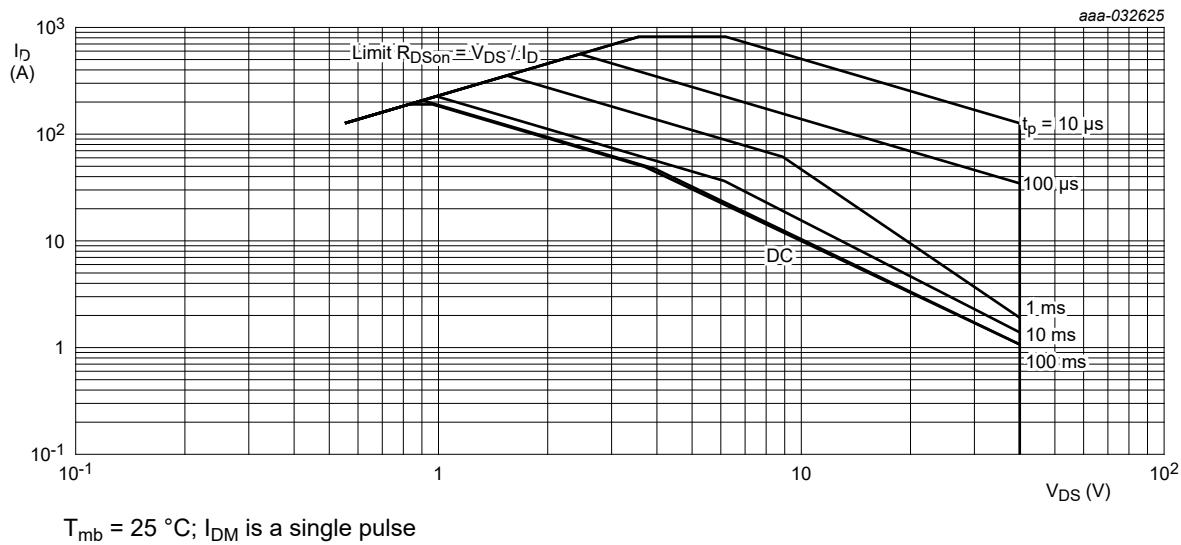
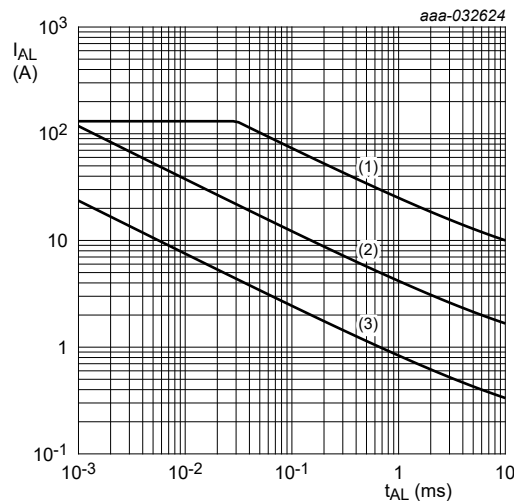


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage



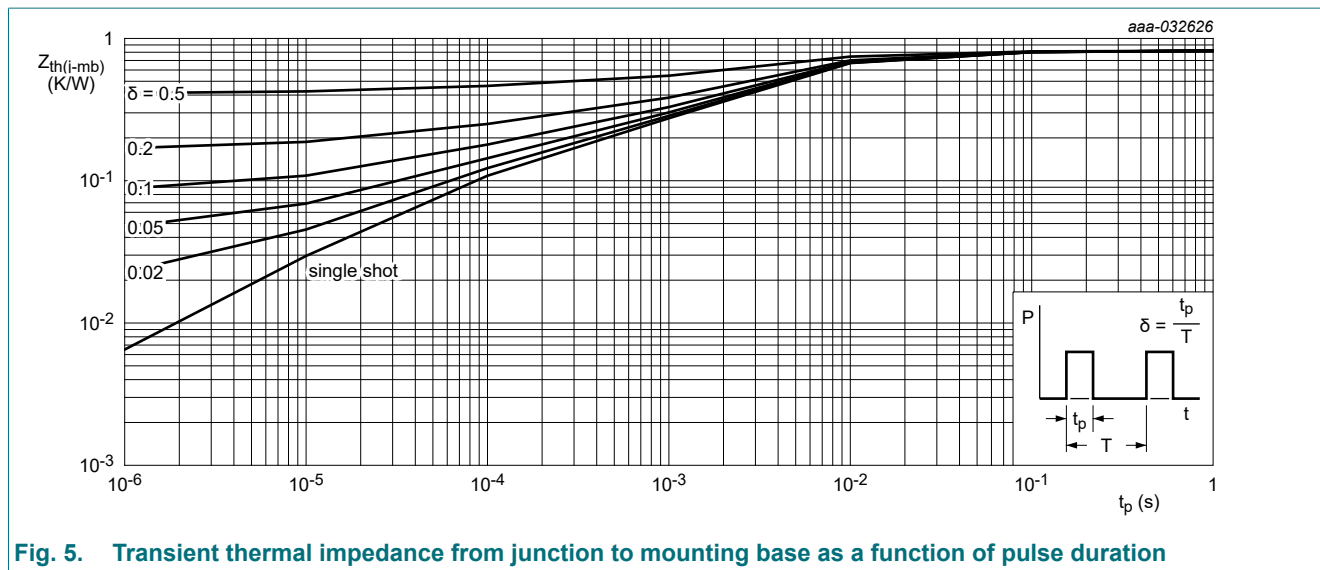
(1) $T_{j\ (init)} = 25^\circ C$; (2) $T_{j\ (init)} = 150^\circ C$; (3) Repetitive Avalanche

Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	0.72	0.82	K/W



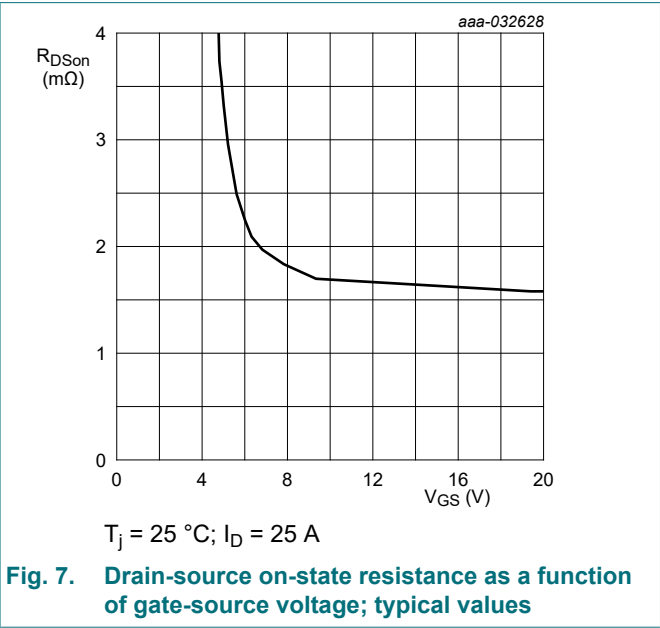
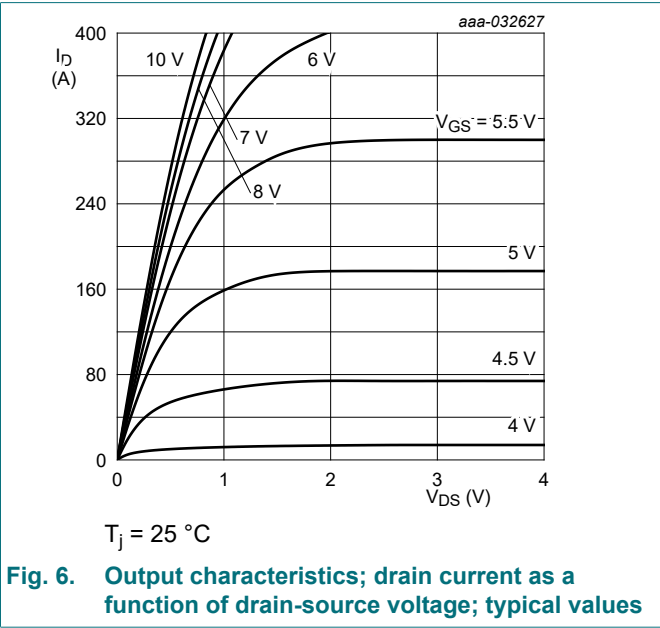
10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_J = 25 ^\circ C$	40	43	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_J = -40 ^\circ C$	-	40.5	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_J = -55 ^\circ C$	36	40	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 mA; V_{DS}=V_{GS}; T_J = 25 ^\circ C; \text{Fig. 9; Fig. 10}$	2.4	3	3.6	V
		$I_D = 1 mA; V_{DS}=V_{GS}; T_J = -55 ^\circ C; \text{Fig. 10}$	-	-	4.3	V
		$I_D = 1 mA; V_{DS}=V_{GS}; T_J = 175 ^\circ C; \text{Fig. 10}$	1	-	-	V
I_{DSS}	drain leakage current	$V_{DS} = 40 V; V_{GS} = 0 V; T_J = 25 ^\circ C$	-	0.06	1	μA
		$V_{DS} = 16 V; V_{GS} = 0 V; T_J = 125 ^\circ C$	-	1.3	10	μA
		$V_{DS} = 40 V; V_{GS} = 0 V; T_J = 175 ^\circ C$	-	133	500	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 V; V_{DS} = 0 V; T_J = 25 ^\circ C$	-	2	100	nA
		$V_{GS} = -10 V; V_{DS} = 0 V; T_J = 25 ^\circ C$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10 V; I_D = 25 A; T_J = 25 ^\circ C; \text{Fig. 11}$	1.19	1.7	2	m Ω
		$V_{GS} = 10 V; I_D = 25 A; T_J = 105 ^\circ C; \text{Fig. 12}$	1.69	2.6	3.18	m Ω
		$V_{GS} = 10 V; I_D = 25 A; T_J = 125 ^\circ C; \text{Fig. 12}$	1.87	2.83	3.5	m Ω
		$V_{GS} = 10 V; I_D = 25 A; T_J = 175 ^\circ C; \text{Fig. 12}$	2.34	3.55	4.36	m Ω
R_G	gate resistance	$f = 1 MHz; T_J = 25 ^\circ C$	0.36	0.89	2.23	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 25 A; V_{DS} = 32 V; V_{GS} = 10 V; \text{Fig. 13; Fig. 14}$	-	50	70	nC
Q_{GS}	gate-source charge		-	14	21	nC
Q_{GD}	gate-drain charge		-	9	18	nC

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
C _{iss}	input capacitance	V _{DS} = 25 V; V _{GS} = 0 V; f = 1 MHz; T _j = 25 °C; Fig. 15		-	3625	5075	pF
C _{oss}	output capacitance			-	950	1330	pF
C _{rss}	reverse transfer capacitance			-	156	343	pF
t _{d(on)}	turn-on delay time	V _{DS} = 30 V; R _L = 1.2 Ω; V _{GS} = 10 V; R _{G(ext)} = 5 Ω		-	12.2	-	ns
t _r	rise time			-	10.4	-	ns
t _{d(off)}	turn-off delay time			-	29	-	ns
t _f	fall time			-	14	-	ns
Source-drain diode							
V _{SD}	source-drain voltage	I _S = 25 A; V _{GS} = 0 V; T _j = 25 °C; Fig. 16		-	0.74	1	V
t _{rr}	reverse recovery time	I _S = 25 A; dI _S /dt = -100 A/μs; V _{GS} = 0 V; V _{DS} = 20 V; T _j = 25 °C		-	32.6	-	ns
Q _r	recovered charge		[1]	-	25	-	nC
S	softness factor			-	0.88	-	
		I _S = 25 A; dI _S /dt = -500 A/μs; V _{GS} = 0 V; V _{DS} = 20 V; T _j = 25 °C		-	0.73	-	

[1] includes capacitive recovery



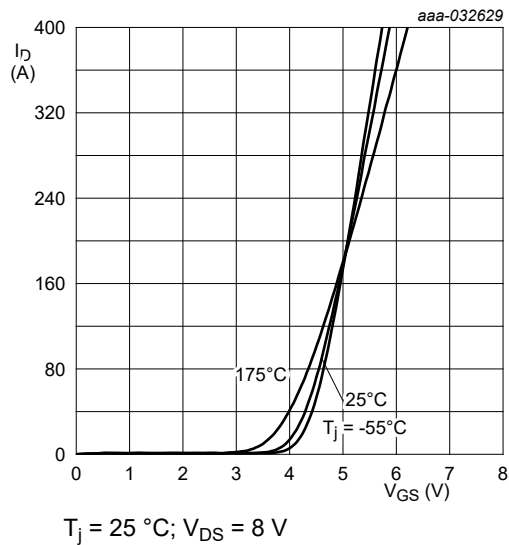


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

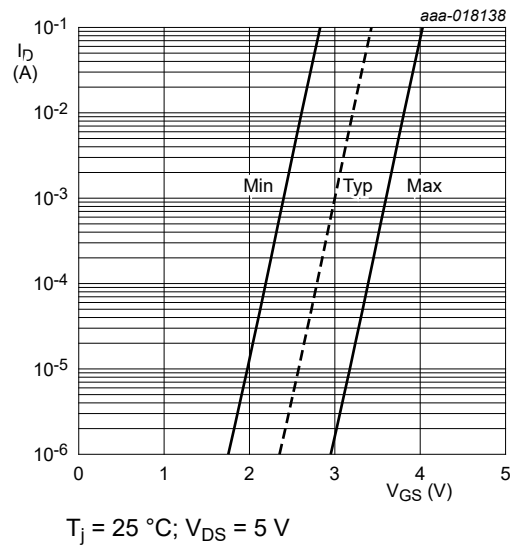


Fig. 9. Sub-threshold drain current as a function of gate-source voltage

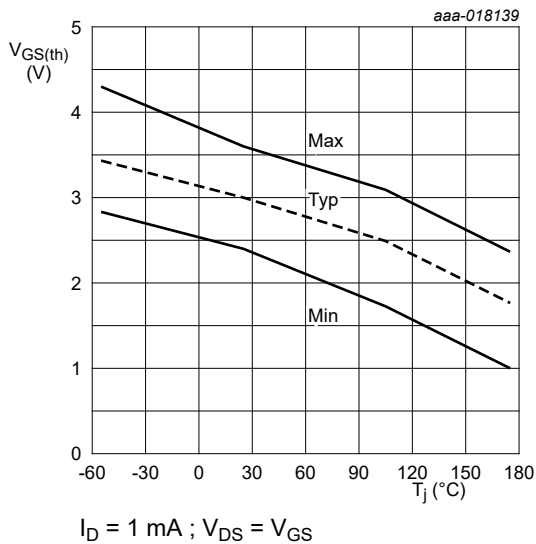


Fig. 10. Gate-source threshold voltage as a function of junction temperature

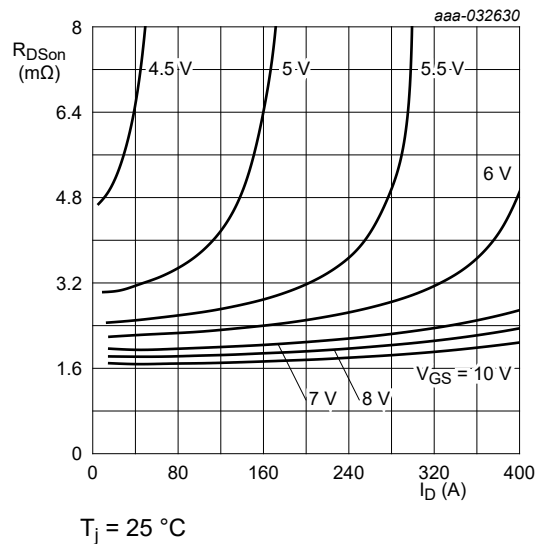


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

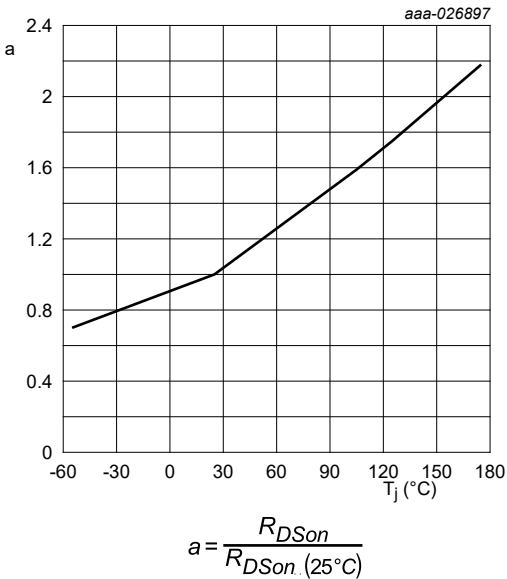


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

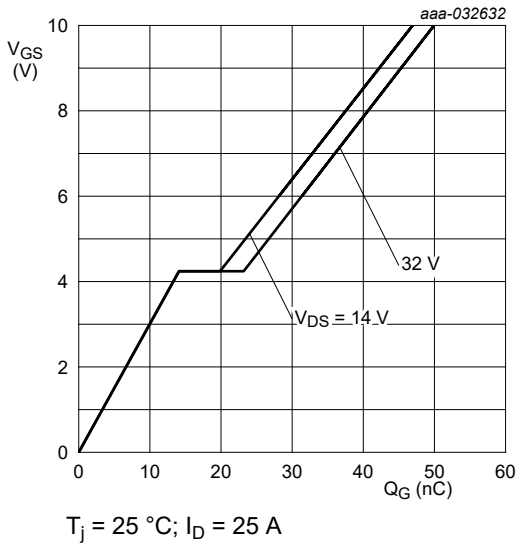


Fig. 13. Gate-source voltage as a function of gate charge; typical values

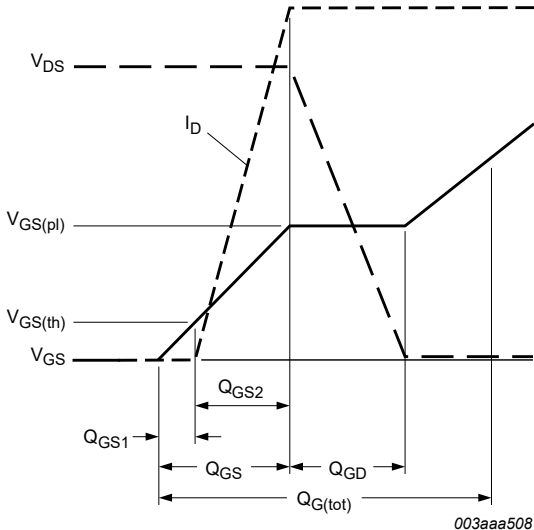


Fig. 14. Gate charge waveform definitions

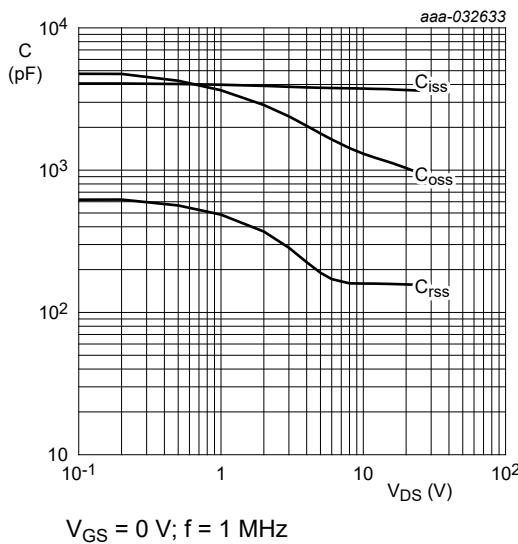
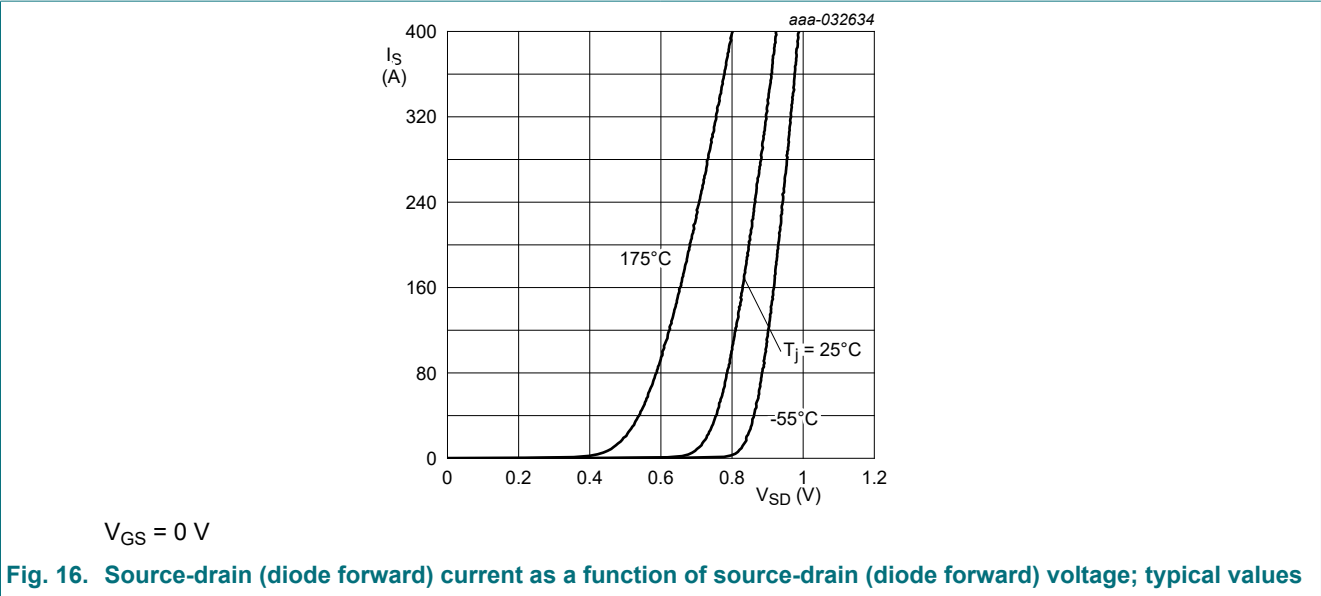


Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



11. Package outline

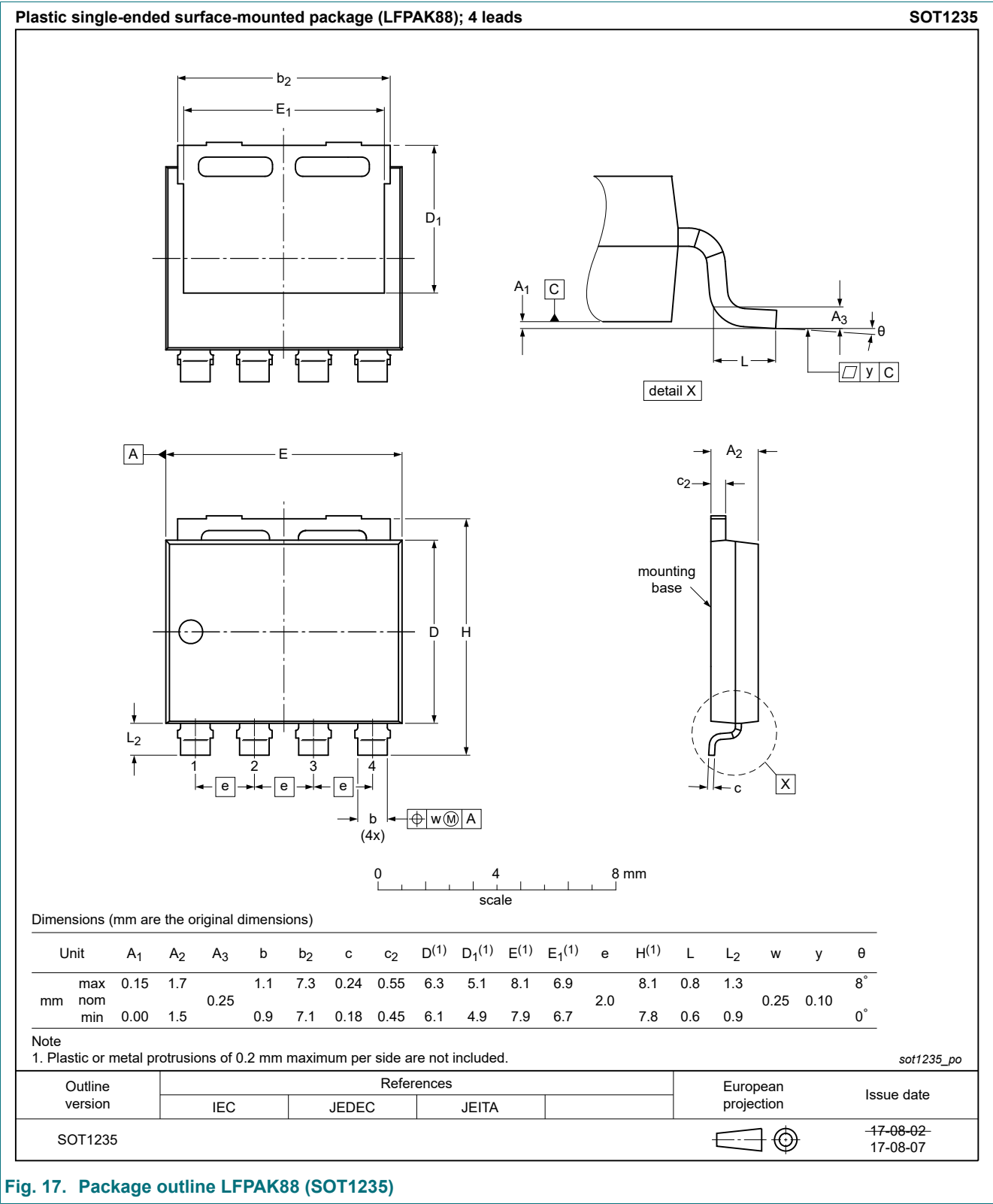


Fig. 17. Package outline LPAK88 (SOT1235)

12. Soldering

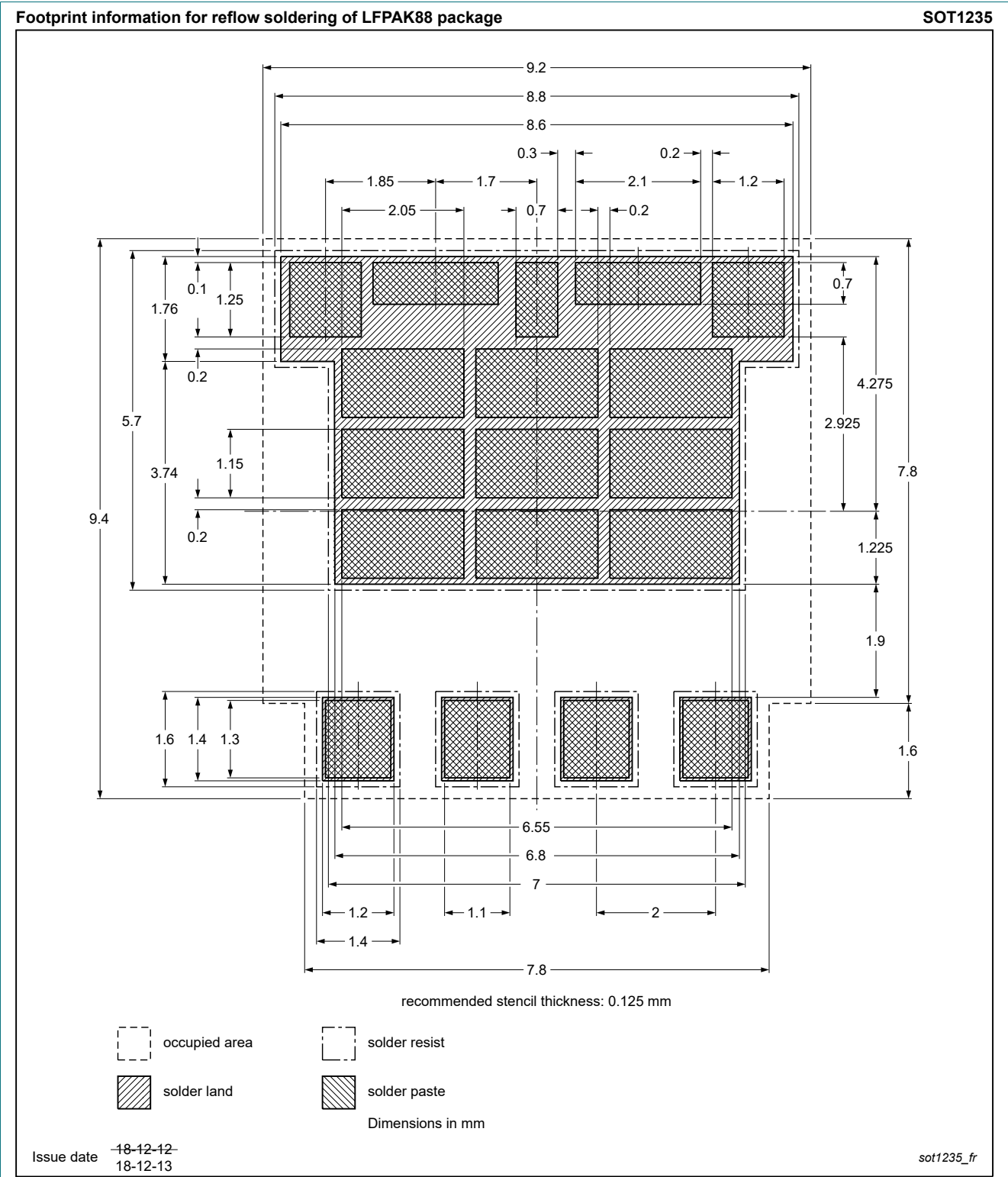


Fig. 18. Reflow soldering footprint for LPAK88 (SOT1235)

13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Contents

1. General description..... 1

2. Features and benefits..... 1

3. Applications..... 1

4. Quick reference data..... 1

5. Pinning information.....2

6. Ordering information.....2

7. Marking.....2

8. Limiting values..... 2

9. Thermal characteristics..... 4

10. Characteristics..... 5

11. Package outline..... 10

12. Soldering..... 11

13. Legal information.....12

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